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Debbie G. Senesky
Sachin Dekate
Editors

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Contents

vii	Conference Committee
ix	Introduction

SESSION 1 RADIATION-TOLERANT DEVICES

- 9113 02 **The effects of gamma irradiation on micro-hotplates with integrated temperature sensing diodes (Invited Paper)** [9113-1]
L. A. Francis, N. André, E. H. Boufouss, P. Gérard, Univ. Catholique de Louvain (Belgium); Z. Ali, Cambridge CMOS Sensors (United Kingdom); F. Udreá, Cambridge CMOS Sensors (United Kingdom) and Univ. of Cambridge (United Kingdom); D. Flandre, Univ. Catholique de Louvain (Belgium)
- 9113 04 **Effects of radiation and temperature on gallium nitride (GaN) metal-semiconductor-metal ultraviolet photodetectors** [9113-3]
H. C. Chiamori, Stanford Univ. (United States); C. Angadi, NASA Ames Research Ctr. (United States); A. Suria, A. Shankar, M. Hou, Stanford Univ. (United States); S. Bhattacharya, NASA Ames Research Ctr. (United States); D. G. Senesky, Stanford Univ. (United States)

SESSION 2 HIGH-TEMPERATURE SENSING TECHNOLOGY

- 9113 05 **Silicon carbide solid state photomultiplier for UV light detection** [9113-5]
S. Soloviev, S. Dolinsky, S. Palit, X. Zhu, P. Sandvik, GE Global Research (United States)
- 9113 06 **4H-SiC PN diode for extreme environment temperature sensing applications** [9113-6]
N. Zhang, C.-M. Lin, Y. Rao, Univ. of California, Berkeley (United States); D. G. Senesky, Stanford Univ. (United States); A. P. Pisano, Univ. of California, Berkeley (United States)

SESSION 3 MEMS FOR HARSH ENVIRONMENTS

- 9113 08 **High temperature SiC pressure sensors with low offset voltage shift (Invited Paper)** [9113-9]
R. S. Okojie, NASA Glenn Research Ctr. (United States); D. Lukco, Vantage Partners, LLC (United States) and NASA Glenn Research Ctr. (United States); V. Nguyen, E. Savrun, Sienna Technologies, Inc. (United States)
- 9113 09 **Mechanical properties of MEMS materials: reliability investigations by mechanical- and HRXRD-characterization related to environmental testing (Invited Paper)** [9113-10]
T. Bandi, Ctr. Suisse d'Electronique et de Microtechnique SA (Switzerland) and Ecole Polytechnique Fédérale de Lausanne (Switzerland); H. Shea, Ecole Polytechnique Fédérale de Lausanne (Switzerland); A. Neels, Ctr. Suisse d'Electronique et de Microtechnique SA (Switzerland)

- 9113 0A **Development of an aluminum nitride-silicon carbide material set for high-temperature sensor applications (Invited Paper)** [9113-11]
B. A. Griffin, S. D. Habermehl, P. J. Clews, Sandia National Labs. (United States)
- 9113 0B **Characterization of irradiated and temperature-compensated gallium nitride surface acoustic wave resonators** [9113-12]
A. Shankar, Stanford Univ. (United States); C. Angadi, Delft Univ. of Technology (Netherlands) and NASA Ames Research Ctr. (United States); S. Bhattacharya, NASA Ames Research Ctr. (United States); C.-M. Lin, Silicon Labs., Inc. (United States); D. G. Senesky, Stanford Univ. (United States)
- 9113 0C **High temperature energy harvesters utilizing ALN/3C-SiC composite diaphragms** [9113-13]
Y.-J. Lai, W.-C. Li, Univ. of California, Berkeley (United States); V. V. Felmetzger, OEM Group, Inc. (United States); D. G. Senesky, Stanford Univ. (United States); A. P. Pisano, Univ. of California, Berkeley (United States) and Univ. of California, San Diego (United States)
- 9113 0D **Emerging GaN-based HEMTs for mechanical sensing within harsh environments** [9113-14]
H. Köck, Stanford Univ. (United States) and Kompetenzzentrum Automobil- u. Industrieelektronik GmbH (Austria); C. A. Chapin, Stanford Univ. (United States); C. Ostermaier, O. Häberlen, Infineon Technologies Austria AG (Austria); D. G. Senesky, Stanford Univ. (United States)

SESSION 4 FIBER OPTIC SYSTEMS

- 9113 0E **Monitoring corrosion in reinforced concrete structures (Invited Paper)** [9113-15]
P. Kung, QPS Photonics Inc. (Canada); M. I. Comanici, McGill Univ. (Canada)
- 9113 0F **Rainfall compensation scheme in distributed optical-fiber vibration sensor engineering system** [9113-17]
H. Zhu, C. Pan, X. Sun, Southeast Univ. (China)
- 9113 0G **A miniaturized optical package for wall shear stress measurements in harsh environments** [9113-18]
T.-A. Chen, D. Mills, V. Chandrasekharan, M. Sheplak, Univ. of Florida (United States)
- 9113 0H **Development of a sapphire optical pressure sensor for high-temperature applications** [9113-19]
D. A. Mills, D. Alexander, G. Subhash, M. Sheplak, Univ. of Florida (United States)

SESSION 5 INDUSTRIAL APPLICATIONS

- 9113 0I **Robust MEMS gyroscope for oil and gas exploration (Invited Paper)** [9113-20]
D. Lin, T. Miller, General Electric Global Research (United States)
- 9113 0J **Development of a downhole tool measuring real-time concentration of ionic tracers and pH in geothermal reservoirs** [9113-21]
R. F. Hess, T. J. Boyle, S. Limmer, W. G. Yelton, S. Bingham, Sandia National Labs. (United States); G. Stillman, U. S. Dept. of Energy (United States); S. Lindblom, G. Cieslewski, Sandia National Labs. (United States)

SESSION 6 SPACE ENVIRONMENT AND EXPLORATION

- 9113 0M **Magnetoresistive sensors for angle, position, and electrical current measurement in demanding environments** [9113-24]
M. Doms, R. Slatter, Sensitec GmbH (Germany)
- 9113 0N **Planetary Atmospheres Minor Species Sensor (PAMSS)** [9113-25]
D. Maukonen, C. J. Fredricksen, A. V. Muraviev, A. Alhasan, S. Calhoun, G. Zummo, R. E. Peale, J. E. Colwell, Univ. of Central Florida (United States)
- 9113 0Q **Qualification of quantum cascade lasers for space environments** [9113-29]
T. L. Myers, B. D. Cannon, C. S. Brauer, Pacific Northwest National Lab. (United States); B. G. Crowther, Utah State Univ. (United States); S. M. Hansen, Utah State Univ. (United States) and Space Dynamics Lab. (United States)

POSTER SESSION

- 9113 0S **Noise estimation technique to reduce the effects of 1/f noise in Open Path Tunable Diode Laser Absorption Spectrometry (OP-TDLAS)** [9113-41]
I. L. Mohammad, Univ. of Arkansas at Little Rock (United States) and The Univ. of Mustansiriyah (Iraq); G. T. Anderson, Y. Chen, Univ. of Arkansas at Little Rock (United States)

Author Index

Conference Committee

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Introduction

The inaugural conference on Sensors for Extreme Harsh Environments showcased recent results from members of this unique and emerging community. During this conference, insights on the performance and design considerations of sensor materials, devices and systems within harsh radiation, temperature and chemical environments were presented. In addition, the requirements for implementing these new technologies on actual commercial (automotive and geothermal power) and space/defense platforms (space rovers and hypersonic structures) were highlighted. A roadmap for addressing the challenges of integrating and manufacturing reliable micro- and nano-scale devices for harsh environment sensing applications was discussed. Representation from academia, industry and government agencies provided a comprehensive audience. Also, participants from overseas—Belgium, Austria, Germany and Taiwan—aided in obtaining a global view of the challenges of this field.

We would like to thank our esteemed colleagues for making it an insightful and productive conference. We are thrilled to share your hard work and exciting results through this proceedings volume. We look forward to building upon our initial success at DSS 2015!

Debbie G. Senesky
Sachin Dekate